

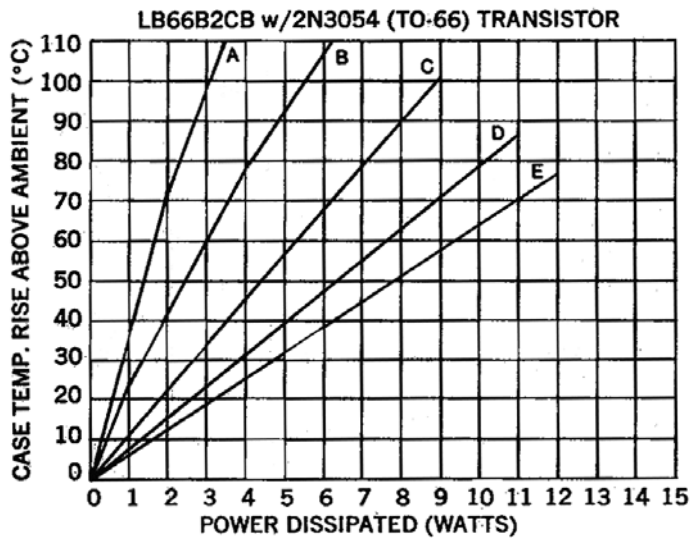
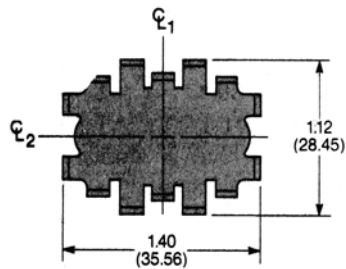
### METAL CASE, CASE-MOUNTED SEMICONDUCTORS

Part Number Series LB66B2

Natural Conv. (°C/W): 19.7

Forced Air (°C/W): 6.4

Mounting Envelope: 1.40" x 1.12" x .31"



#### DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Mounted to G-10.
- B. N.C Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss.
- D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.

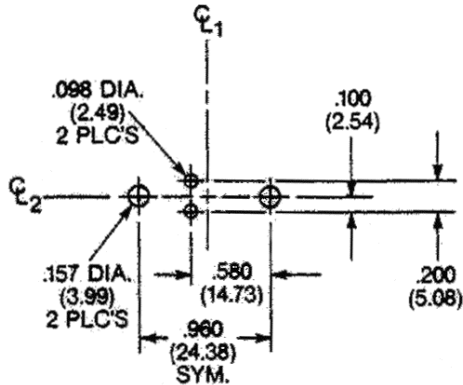
- Thermal Resistance Case to Sink is 0.5-0.7 °C/W w/Joint Compound.
- Derate 1.4 °C/watt for unplated part in natural convection only.

## Ordering Information

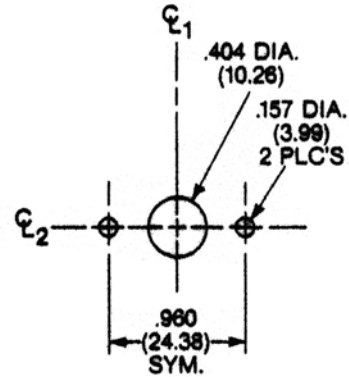
CTS IERC PART NO.			Semiconductor Accommodated	Hole patt. ref. no.	Max. Weight (Grams)
Unplated	Comm'l. Black Anodize	Mil. Black Anodize			
LB66B2-76U	LB66B2-76CB	LB66B2-76B	Undrilled	--	4.8
LB66B2U	LB66B2CB	LB66B2B	TO-66	9	4.8
LB66B2-67U	LB66B2-67CB	LB66B2-67B	TO-66 IC	7	4.8
LB66B2-77U	LB66B2-77CB	LB66B2-77B	TO-66 IC (Socket)	10	4.8

### HOLE PATTERNS

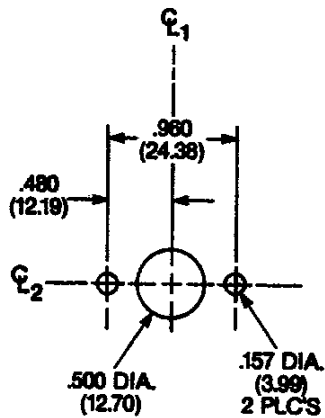
9. Hole Pattern no. 133 accommodates TO-66s. Available in LB series heat dissipators only.



7. Hole pattern no. 191 accommodates To-66 lcs. Available in LA-A, LA-B, and LB series heat dissipators only.



10. Hole pattern no. 225 accommodates TO-66 ICs (socket). Available in LB series heat dissipators only.



### CTS IERC, Heat Sinks and Thermal Management Solutions

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